



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Zuniga-Ortiz, et al. /

Serial No.: 10/001,302 /

Filed: 11/01/01 /

For: Bumpless Wafer Scale Device and Board Assembly

Docket No.: TI-33535

Examiner: Clark, S.V.

Art Unit: 2815

#9/A
Amdt
Unpublished
8/18/03

Amendment under 37 CFR 1.111

Commissioner of Patents
P.O. Box 1450
Alexandria, VA, 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with
the U.S. Postal Service as First Class Mail in an envelope addressed
to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-
1450 on July 14, 2003.


Elizabeth Austin

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 3/13/03. They are respectfully submitted as a full and complete response to that Action. A petition for a one-month extension of time accompanies this response. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.